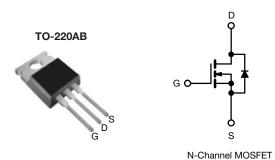


Power MOSFET



PRODUCT SUMMARY				
V _{DS} (V)	400			
$R_{DS(on)}(\Omega)$	V _{GS} = 10 V	0.55		
Q _q max. (nC)	63			

9.0

32

Single

FEATURES

- Dynamic dV/dt rating
- · Repetitive avalanche rated
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION			
Package	TO-220AB		
Lead (Pb)-free	IRF740PbF		
Lead (Pb)-free and halogen-free	IRF740PbF-BE3		

PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	400	V	
Gate-source voltage			V _{GS}	± 20		
Continuous drain current	V _{GS} at 10 V	T _C = 25 °C		10	А	
		$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$	I _D	6.3		
Pulsed drain current ^a			I _{DM}	40	1	
Linear derating factor				1.0	W/°C	
Single pulse avalanche energy ^b			E _{AS}	520	mJ	
Repetitive avalanche current a			I _{AR}	10	А	
Repetitive avalanche energy ^a			E _{AR}	13	mJ	
Maximum power dissipation	T _C =	25 °C	P _D	125	W	
Peak diode recovery dV/dt ^c			dV/dt	4.0	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) ^d	For 10 s			300	7	
Mounting torque	6.00.0*1	0.00 - 140		10	lbf ⋅ in	
	6-32 or M3 screw			1.1	N⋅m	

Notes

Q_{gs} (nC)

Q_{gd} (nC)

Configuration

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = 50 V, starting T_J = 25 °C, L = 9.1 mH, R_g = 25 Ω , I_{AS} = 10 A (see fig. 12)
- c. $I_{SD} \le 10$ A, $dI/dt \le 120$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 150$ °C
- d. 1.6 mm from case



Vishay Siliconix

THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	-	62		
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W	
Maximum junction-to-case (drain)	R _{thJC}	-	1.0		

PARAMETER	SYMBOL	TEST	CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static		•		Į.	!		
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$		400	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	Reference to 25 °C, I _D = 1 mA		0.49	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V$	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$		-	4.0	V
Gate-source leakage	I _{GSS}	V _{GS} = ± 20 V		-	-	± 100	nA
7	,	V _{DS} = 400 V, V _{GS} = 0 V		-	-	25	μА
Zero gate voltage drain current	I _{DSS}	V _{DS} = 320 V, \	V _{DS} = 320 V, V _{GS} = 0 V, T _J = 125 °C		-	250	
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 6.0 A ^b	-	-	0.55	Ω
Forward transconductance	9 _{fs}	V _{DS} = 50 V, I _D = 6.0 A ^b		5.8	-	-	S
Dynamic							
Input capacitance	C _{iss}	$V_{GS} = 0 \text{ V},$ $V_{DS} = 25 \text{ V},$ $f = 1.0 \text{ MHz}, \text{ see fig. } 5$		-	1400	-	pF
Output capacitance	C _{oss}			-	330	-	
Reverse transfer capacitance	C _{rss}			-	120	-	
Total gate charge	Qg		I _D = 10 A, V _{DS} = 320 V, see fig. 6 and 13 ^b	-	-	63	nC
Gate-source charge	Q _{gs}	V _{GS} = 10 V		-	-	9.0	
Gate-drain charge	Q_{gd}			-	-	32	
Turn-on delay time	t _{d(on)}	$V_{DD} = 200 \text{ V, } I_{D} = 10 \text{ A}$ $R_{g} = 9.1 \Omega, R_{D} = 20 \Omega, \text{ see fig. } 10^{\text{ b}}$		-	14	-	- ns
Rise time	t _r			-	27	-	
Turn-off delay time	t _{d(off)}			-	50	-	
Fall time	t _f			-	24	-	
Gate input resistance	Rg	f = 1 MHz, open drain		0.8	-	5.9	Ω
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from package and center of die contact		-	4.5	-	-11
Internal source inductance	L _S			-	7.5	-	- nH
Drain-Source Body Diode Characteristic	es	<u>.</u>					
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	10	^
Pulsed diode forward current ^a	I _{SM}			-	-	40	A
Body diode voltage	V_{SD}	$T_J = 25 ^{\circ}\text{C}, I_S = 10 \text{A}, V_{GS} = 0 \text{V}^{ \text{b}}$		-	-	2.0	V
Body diode reverse recovery time	t _{rr}	T _J = 25 °C, I _F = 10 A, dl/dt = 100 A/µs b		-	370	790	ns
Body diode reverse recovery charge	Q _{rr}			-	3.8	8.2	μC
Forward turn-on time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L				L _D)	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

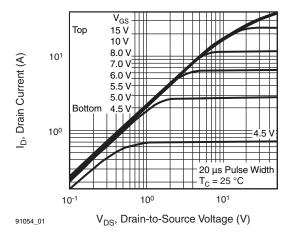


Fig. 1 - Typical Output Characteristics, $T_C = 25$ °C

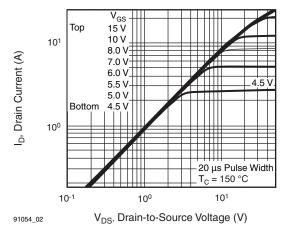


Fig. 2 - Typical Output Characteristics, $T_C = 150$ °C

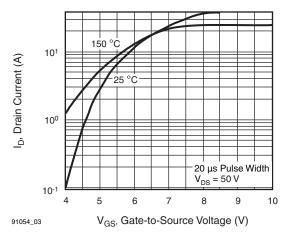


Fig. 3 - Typical Transfer Characteristics

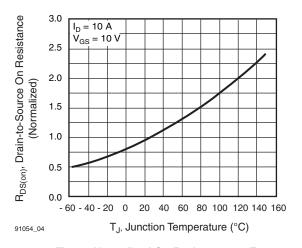


Fig. 4 - Normalized On-Resistance vs. Temperature

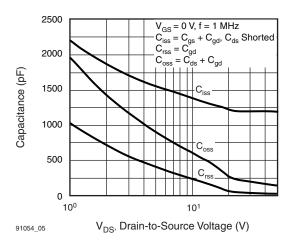


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

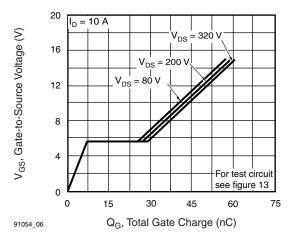


Fig. 6 - Typical Gate Charge vs. Drain-to-Source Voltage



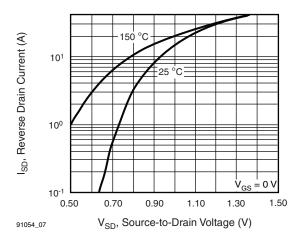


Fig. 7 - Typical Source-Drain Diode Forward Voltage

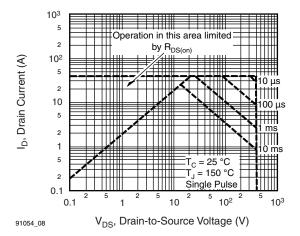


Fig. 8 - Maximum Safe Operating Area

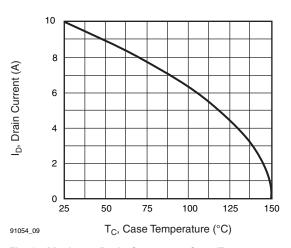


Fig. 9 - Maximum Drain Current vs. Case Temperature

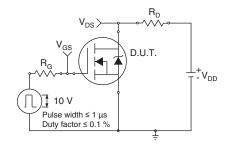


Fig. 10a - Switching Time Test Circuit

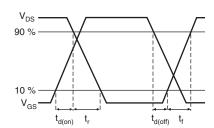


Fig. 10b - Switching Time Waveforms

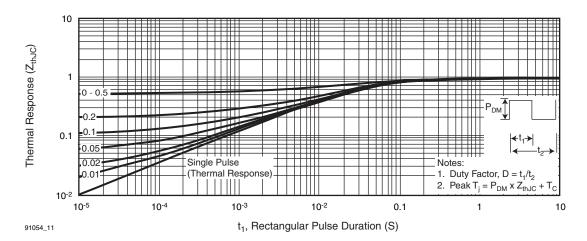
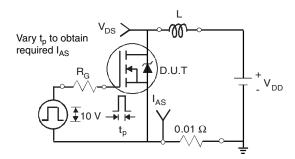
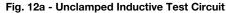




Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case





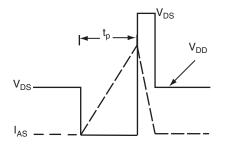


Fig. 12b - Unclamped Inductive Waveforms

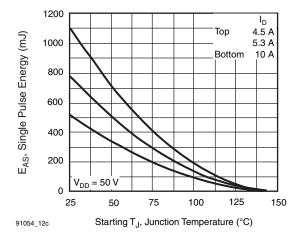


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

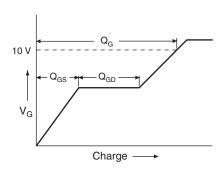


Fig. 13a - Basic Gate Charge Waveform

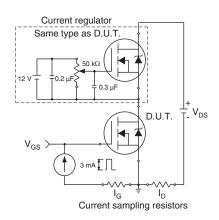


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit

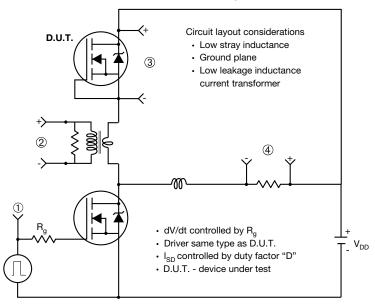




Fig. 14 - For N-Channel

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